



January 1999
Revised March 1999

74LVT245 • 74LVTH245

Low Voltage Octal Bidirectional Transceiver with 3-STATE Inputs/Outputs (Preliminary)

General Description

The LVT245 and LVTH245 contain eight non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus-oriented applications. The Transmit/Receive (T/R) input determines the direction of data flow through the bidirectional transceiver. Transmit (active-HIGH) enables data from A ports to B ports; Receive (active-LOW) enables data from B ports to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a HIGH Z condition.

The LVTH245 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These transceivers are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT245 and LVTH245 are fabricated with an advanced BiCMOS technology to

achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

Features

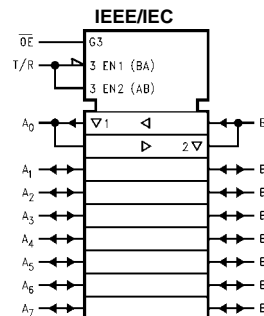
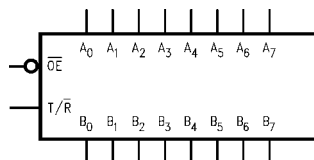
- Input and output interface capability to systems at 5V V_{CC}
- Bus-Hold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH245), also available without bushold feature (74LVT245).
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink, -32 mA/+64 mA
- Latch-up performance exceeds 500 mA

Ordering Code:

Order Number	Package Number	Package Description
74LVT245WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, .300" Wide
74LVT245SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II 5.3mm Wide
74LVT245MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LVT245MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LVTH245WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, .300" Wide
74LVTH245SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II 5.3mm Wide
74LVTH245MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LVTH245MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

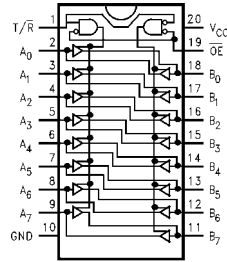
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbols



74LVT245 • 74LVTH245 Low Voltage Octal Bidirectional Transceiver with 3-STATE Inputs/Outputs (Preliminary)

Connection Diagram



Pin Descriptions

Pin Names	Description
\overline{OE}	Output Enable Input
T/\overline{R}	Transmit/Receive Input
A_0-A_7	Side A Inputs or 3-STATE Outputs
B_0-B_7	Side B Inputs or 3-STATE Outputs

Truth Table

Inputs		Outputs
\overline{OE}	T/\overline{R}	
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	HIGH-Z State

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial

Absolute Maximum Ratings ^(Note 1)					
Symbol	Parameter	Value	Conditions		Units
V _{CC}	Supply Voltage	-0.5 to +4.6			V
V _I	DC Input Voltage	-0.5 to +7.0			V
V _O	Output Voltage	-0.5 to +7.0	Output in 3-STATE		V
		-0.5 to +7.0	Output in High or Low State (Note 2)		V
I _{IK}	DC Input Diode Current	-50	V _I < GND		mA
I _{OK}	DC Output Diode Current	-50	V _O < GND		mA
I _O	DC Output Current	64	V _O > V _{CC} Output at HIGH State		mA
		128	V _O > V _{CC} Output at LOW State		
I _{CC}	DC Supply Current per Supply Pin	±64			mA
I _{GND}	DC Ground Current per Ground Pin	±128			mA
T _{STG}	Storage Temperature	-65 to +150			°C

Recommended Operating Conditions					
Symbol	Parameter	Symbol	Min	Max	Units
V _{CC}	Supply Voltage		2.7	3.6	V
V _I	Input Voltage		0	5.5	V
I _{OH}	High-Level Output Current			-32	mA
I _{OL}	Low-Level Output Current			64	mA
T _A	Free Air Operating Temperature		-40	+85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V		0	10	ns/V

Note 1: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 2: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = -40°C to +85°C			Units	Conditions	
			Min	Typ (Note 3)	Max			
V _{IK}	Input Clamp Diode Voltage	2.7			-1.2	V	I _I = -18 mA	
V _{IH}	Input HIGH Voltage	2.7–3.6	2.0			V	V _O ≤ 0.1V or V _O ≥ V _{CC} - 0.1V	
V _{IL}	Input LOW Voltage	2.7–3.6			0.8			
V _{OH}	Output HIGH Voltage	2.7–3.6	V _{CC} - 0.2			V	I _{OH} = -100 μA	
		2.7	2.4			V	I _{OH} = -8 mA	
		3.0	2.0			V	I _{OH} = -32 mA	
V _{OL}	Output LOW Voltage	2.7			0.2	V	I _{OL} = 100 μA	
		2.7			0.5	V	I _{OL} = 24 mA	
		3.0			0.4	V	I _{OL} = 16 mA	
		3.0			0.5	V	I _{OL} = 32 mA	
		3.0			0.55	V	I _{OL} = 64 mA	
I _{I(HOLD)} (Note 4)	Bus-Hold Input Minimum Drive	3.0	75			μA	V _I = 0.8V	
			-75			μA	V _I = 2.0V	
I _{I(OD)} (Note 4)	Bus-Hold Input Over-Drive Current to Change State	3.0	500			μA	(Note 5)	
			-500			μA	(Note 6)	
I _I	Input Current	3.6			10	μA	V _I = 5.5V	
			Control Pins	3.6		±1	μA	V _I = 0V or V _{CC}
			Data Pins	3.6		-5	μA	V _I = 0V
						1	μA	V _I = V _{CC}
I _{OFF}	Power Off Leakage Current	0			±100	μA	0V ≤ V _I or V _O ≤ 5.5V	
I _{PU/PD} (Note 7)	Power Up/Down 3-STATE Current	0–1.5V			±100	μA	V _O = 0.5V to V _{CC} V _I = GND to V _{CC}	
I _{OZL}	3-STATE Output Leakage Current	3.6			-5	μA	V _O = 0.5V	
I _{OZH}	3-STATE Output Leakage Current	3.6			5	μA	V _O = 3.0V	

DC Electrical Characteristics (Continued)

Symbol	Parameter	V _{CC} (V)	T _A = -40°C to +85°C			Units	Conditions
			Min	Typ (Note 3)	Max		
I _{OZH} ⁺	3-STATE Output Leakage Current	3.6			10	μA	V _{CC} < V _O ≤ 5.5V
I _{CCH}	Power Supply Current	3.6			0.19	mA	Outputs High
I _{CCL}	Power Supply Current	3.6			5	mA	Outputs Low
I _{CCZ}	Power Supply Current	3.6			0.19	mA	Outputs Disabled
I _{CCZ} ⁺	Power Supply Current	3.6			0.19	mA	V _{CC} ≤ V _O ≤ 5.5V, Outputs Disabled
ΔI _{CC}	Increase in Power Supply Current (Note 7)	3.6			0.2	mA	One Input at V _{CC} - 0.6V Other Inputs at V _{CC} or GND

Note 3: All typical values are at V_{CC} = 3.3V, T_A = 25°C.

Note 4: Applies to Bushold versions only (LVTH245).

Note 5: An external driver must source at least the specified current to switch from LOW to HIGH.

Note 6: An external driver must sink at least the specified current to switch from HIGH to LOW.

Note 7: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 8)

Symbol	Parameter	V _{CC} (V)	T _A = 25°C			Units	Conditions C _L = 50 pF, R _L = 500Ω
			Min	Typ	Max		
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3		0.8		V	(Note 9)
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3		-0.8		V	(Note 9)

Note 8: Characterized in SOIC package. Guaranteed parameter, but not tested.

Note 9: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

Symbol	Parameter	T _A = -40°C to +85°C C _L = 50 pF, R _L = 500Ω					Units
		V _{CC} = 3.3V ±0.3V			V _{CC} = 2.7V		
		Min	Typ (Note 10)	Max	Min	Max	
t _{PLH}	Propagation Delay	1.2		3.5	1.2	4.0	ns
t _{PHL}		1.2		3.5	1.2	4.0	
t _{PZH}	Output Enable Time	1.3		5.5	1.3	7.1	ns
t _{PZL}		1.7		5.5	1.7	6.5	
t _{PHZ}	Output Disable	2.2		5.9	2.2	6.5	ns
t _{PLZ}		2.2		5.0	2.2	5.1	
t _{OSSL}	Output to Output Skew (Note 11)			1.0		1.0	ns
t _{OSLH}							

Note 10: All typical values are at V_{CC} = 3.3V, T_A = 25°C.

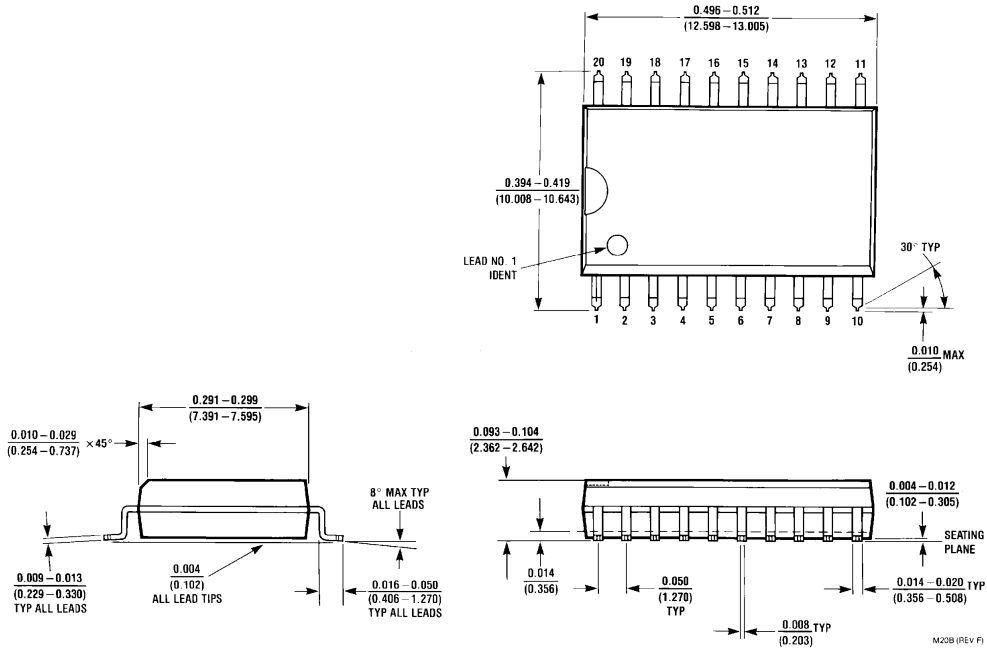
Note 11: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH to LOW (t_{OSSL}) or LOW to HIGH (t_{OSLH}).

Capacitance (Note 12)

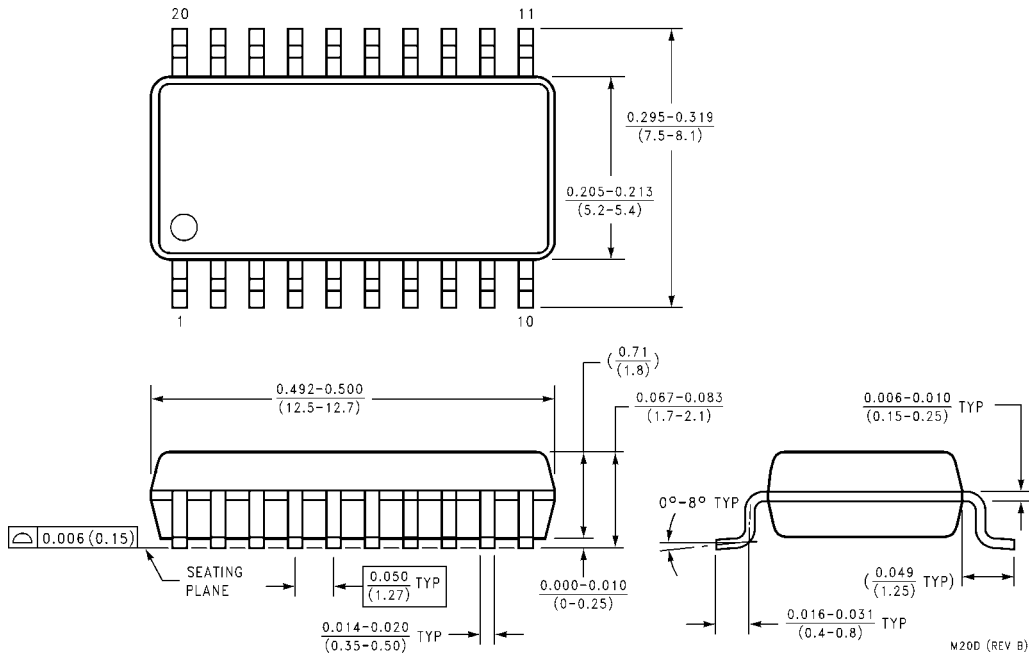
Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = 0V, V _I = 0V or V _{CC}	4	pF
C _{IO}	Input/Output Capacitance	V _{CC} = 3.0V, V _O = 0V or V _{CC}	8	pF

Note 12: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted



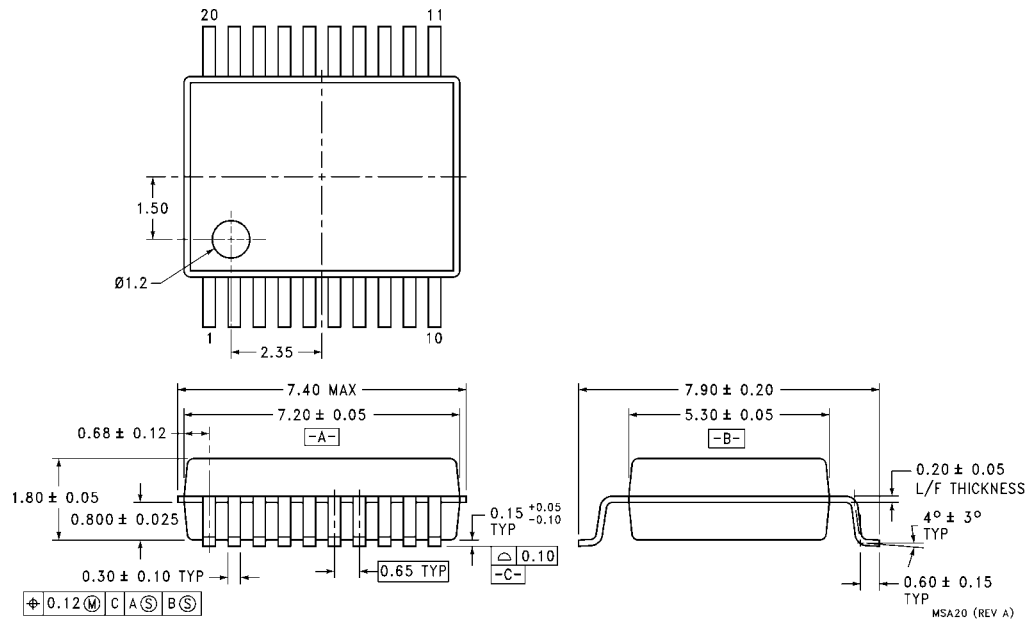
**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, .300" Wide
Package Number M20B**



**20-Lead Small Outline Package (SOP), EIAJ TYPE II 5.3mm Wide
Package Number M20D**

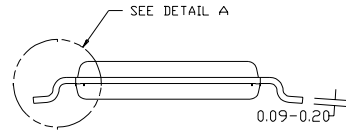
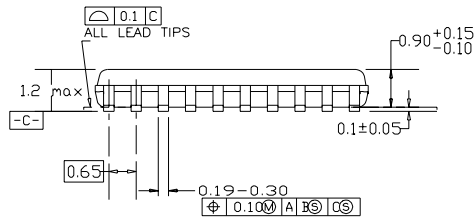
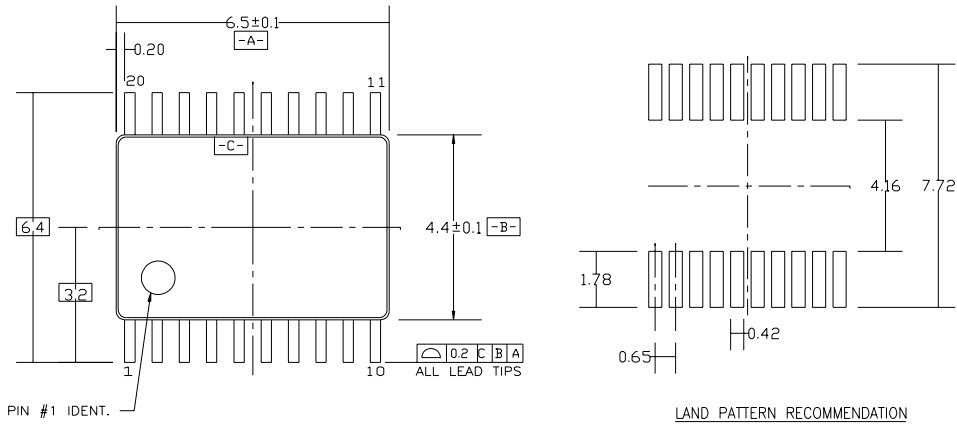
74LVT245 • 74LVTH245

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

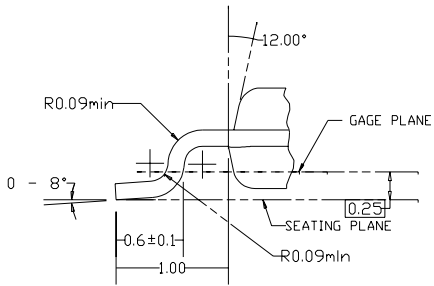


**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com